

ON Semiconductor				10/15/2019
Base Part		NC7SZ19	HF	Pb-free
Orderable Part		NC7SZ19FHX	Total weight (mg)	1.397
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.111	Silicon (Si)	7440-21-3	100
Die Attach	0.014	Phenolic Resin-2	54208-63-8	28.57142857
		Ortho Cresol Novolac Resin	29690-82-2	71.42857143
Lead Frame	0.402	Zinc (Zn)	7440-66-6	0
		Iron (Fe)	7439-89-6	2.23880597
		Copper (Cu)	7440-50-8	97.76119403
Mold Compound-Black	0.852	Tetramethylbiphenyldiglycidyl Ether	85954-11-6	5.98591549
		Carbon Black (C)	1333-86-4	0.46948357
		Fused Silica (SiO2)	60676-86-0	89.55399061
		Phenolic Resin (Novolac)	9003-35-4	3.99061033
Plating	0.014	Palladium (Pd)	7440-05-3	7.14285714
		Nickel (Ni)	7440-02-0	92.85714286
		Gold (Au)	7440-57-5	0
Wire Bond - Au	0.004	Gold (Au)	7440-57-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at: http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				